



 Masach Technologies Board Level Shielding Design & fabrication	Item No:	Description:	Material:
	MS223-10	DRAWN RF SHEILD FRAME + COVER	TIN STEEL (See Note 1-2)
	Note: (1) TS275E 8.4/8.4 (2) Electrolytic Tin Plate As Per EN 10202:2001 Min Tin Thickness 3.5 µm (3) General tolerance ±0.2mm Non Dimensioned items remain Masach Technologies LTD property.		
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